

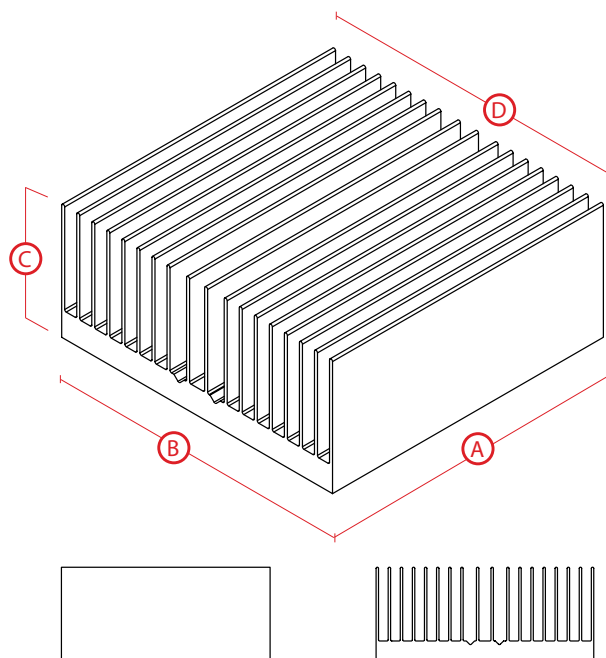


# High Performance BGA Cooling Solutions w/ Thermal Tape Attachment

**ATS PART # ATS-54425R-C2-R0**

## Features & Benefits

- » High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- » Designed specifically for BGAs and other surface mount packages
- » Comes preassembled with high performance thermal interface material



*\*Image above is for illustration purposes only.*

## Thermal Performance

| AIR VELOCITY |     | THERMAL RESISTANCE   |                    |
|--------------|-----|----------------------|--------------------|
| FT/MIN       | M/S | °C/W (UNDUCTED FLOW) | °C/W (DUCTED FLOW) |
| 200          | 1.0 | 3                    | 1.7                |
| 300          | 1.5 | 2.2                  |                    |
| 400          | 2.0 | 1.9                  |                    |
| 500          | 2.5 | 1.6                  |                    |
| 600          | 3.0 | 1.5                  |                    |
| 700          | 3.5 | 1.4                  |                    |
| 800          | 4.0 | 1.3                  |                    |

## Product Details

| DIMENSION A | DIMENSION B | DIMENSION C | DIMENSION D | INTERFACE MATERIAL | FINISH         |
|-------------|-------------|-------------|-------------|--------------------|----------------|
| 42.5 mm     | 42.5 mm     | 19.5 mm     | 42.5 mm     | SAINT-GOBAIN C675  | BLACK-ANODIZED |

### NOTES:

- 1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
- 2) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 3) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 4) Contact ATS to learn about custom options available.



**For more information, to find a distributor or to place an order, visit [www.qats.com](http://www.qats.com) or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).**